

## **1.5 Amp Negative Adjustable Regulator**

### Description

The SGR137/SGR137A is fit, form and function compatible to the SG137/SG137A with the addition of guaranteed performance after radiation exposure to Total Ionizing Dose (TID), Enhanced Low Dose Rate Sensitivity (ELDRS), and Single Event Latch-up (SEL) conditions. The SGR137A family of negative adjustable regulators deliver up to 1.5A output current over an output voltage range of -1.2V to -37V. The device includes significant improvements, such as better line and load regulation, and a maximum output voltage error of 1%. The SGR137 family uses the same chip design and guarantees maximum output voltage error of  $\pm 2\%$ .

Every effort is made to make these devices easy to use and difficult to damage. Internal current and power limiting coupled with true thermal limiting prevents device damage due to overloads or shorts even if the regulator is not fastened to a heat sink.

The SGR137/SGR137A family of products are ideal complements to the SGR117A/117 adjustable positive voltage regulators.

#### **Features**

- 1% Output Voltage Tolerance
- 0.01%/V Line Regulation
- 0.5% Load Regulation
- 0.02%/W Thermal Regulation
- Available in Hermetic TO-220

#### High Reliability Features -SGR137/SGR137A

- Rad-tolerance:(Test data available)
- TID to a Minimum of 50krad(Si)
- ELDRS to a Minimum of 50krad(Si)
- SEL Immunity to a Minimum of 87MeV-cm<sup>2</sup>/mg



## **Typical Application**

Figure 1 - Typical Application





Figure 2 - Resistor Precision vs. Output Voltage Error

## **Connection Diagrams and Ordering Information**

Ambient Temperature	Туре	Package	Part Number	Packaging Type	Connection Diagram	
			SGR137AK		ADJ	
-55°C to 125°C	к	3-Terminal Metal Can	SGR137AK-EV*	TO-3		
123 0	ĸ		SGR137K	10-3		
			SGR137K-EV*		V <sub>OUT</sub> CASE IS V <sub>IN</sub>	
			SGR137AT			
-55°C to	т	3-Terminal Metal Can	SGR137AT-EV*	TO-39	ADJ (1)	
125°C			SGR137T		V <sub>OUT</sub> 2 3 V <sub>IN</sub>	
			SGR137T-EV*		CASE IS VIN	
			SGR137AIG			
-55°C to	IG	3-Pin Hermetic To-257	SGR137AIG-EV*	TO-257 (Isolated)	νουτ	
125°C			SGR137IG		V <sub>IN</sub> ADJ	
			SGR137IG-EV*			

\* EV is Microsemi's "Equivalent V" flow that follows MIL-PRF-38535 requirements for Class V processing.

## **Connection Diagrams and Ordering Information**

Ambient Temperature	Туре	Package	Part Number	Packaging Type	Connection Diagram
			SGR137AL		4 5 5 7 8 8 8 8 8 8 8 8 8 8 8 8 8 8 8 8 8
-55°C to		20-Pin	SGR137AL-EV* Ceramic (LCC)	SGR137AL-EV* Ceramic <sup>6</sup> / <sub>8</sub>	6         5. N.C.         15. N.C.           6         (16         6. N.C.         16. ADJ           7         (15         7. N.C.         17. N.C.
125°C	L	CERAMIC	SGR137L	Leadless Chip Carrier	9 10 11 12 13 L PACKAGE (Top View)
			SGR137L-EV*		PbSn Lead Finish * Both V <sub>OUT</sub> pins must be externally connected together at the device terminals.
<i>Notes:</i> All parts are view	ved from the	e top.	1	1	I

\* EV is Microsemi's "Equivalent V" flow that follows MIL-PRF-38535 requirements for Class V processing.



## Absolute Maximum Ratings<sup>1</sup>

Parameter	Value	Units
Power Dissipation	Internally Limited	-
Input to Output Voltage Differential	40	V
Storage Temperature Range	-65 to 150	°C
Operating Junction Temperature	150	°C
Lead Temperature (Soldering, 10 Seconds)	300	°C

Notes:

1. Stresses above those listed in "ABSOLUTE MAXIMUM RATINGS", may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. All voltages are with respect to Ground. Currents are positive into, negative out of specified terminal.

## **Thermal Data**

Parameter	Value	Units
K Package:		
Thermal Resistance-Junction to Leads, $\theta_{JC}$	3.0	°C/W
Thermal Resistance-Junction to Ambient, $\theta_{JA}$	35	°C/W
T Package:		
Thermal Resistance-Junction to Leads, $\theta_{JC}$	15	°C/W
Thermal Resistance-Junction to Ambient, $\theta_{JA}$	120	°C/W
IG Package:		
Thermal Resistance-Junction to Leads, $\theta_{JC}$	3.5	°C/W
Thermal Resistance-Junction to Ambient, $\theta_{JA}$	42	°C/W
L Package:		
Thermal Resistance-Junction to Leads, $\theta_{JC}$	35	°C/W
Thermal Resistance-Junction to Ambient, $\theta_{JA}$	120	°C/W
Notes	•	

Notes:

• Junction Temperature Calculation:  $T_J = T_A + (P_D x \theta_{JA})$ .

• The above numbers for  $\theta_{JC}$  are maximums for limiting the thermal resistance of the package in a standard mounting configuration. The  $\theta_{JA}$  numbers are the guidelines for the thermal performance of the device/pcboard system. All of the above assume no ambient airflow.

# Recommended Operating Conditions<sup>2-3</sup>

Symbol	Parameter	Recommended	Recommended Operating Conditions					
		Min	Тур	Max	Units			
V <sub>OUT</sub>	Input Voltage Range	-( V <sub>OUT</sub>  +3.5V)		-36	V			
Operating	Operating Junction Temperature Range							
	SGR137A/SGR137	-55		150	°C			
Note: 2. Range over which the device is functional. 3. These ratings are applicable for junction temperatures of less than 135°C.								



## **Electrical Characteristics**

Unless otherwise specified, these specifications apply over full operating ambient temperatures for SGR137A/SGR137 with -55°C  $\leq T_J \leq 150$ °C,  $|V_{IN} - V_{OUT}| = 5.0$ V, and for  $I_{OUT} = 500$ mA (K and IG power packages), and  $I_{OUT} = 100$ mA (T and L packages). Although power dissipation is internally limited, these specifications are applicable for power dissipations of 2W for the T and L packages, and 20W for the K and IG packages. I<sub>MAX</sub> is 1.5A for the K and IG packages and 0.5A for the T and L packages. Low duty cycle pulse testing techniques are used which maintains junction and case temperatures equal to the ambient temperature.

Symbol	Test Conditions	S	SGR137A			SGR137		
		Min.	Min. Typ. Max Min. 1		Тур.	'Units Max		
<u>_</u>	$I_{OUT} = 10mA, T_J = 25^{\circ}C$		-1.250	-1.262	-1.225	-1.250	-1.275	V
Reference Voltage <sup>6</sup>	$3V \le  V_{IN} - V_{OUT}  \le 40V, 10mA \le I_{OUT} \le I_{MAX}$	-1.220	-1.250	-1.280	-1.200	-1.250	-1.300	V
Line Regulation 4,6	$3V \le  V_{IN} - V_{OUT}  \le 40V, I_{OUT} \le I_{MAX}$							
	$T_J = 25^{\circ}C$		0.005	0.01		0.01	0.02	%/V
	$10\text{mA} \le I_{\text{OUT}} \le I_{\text{MAX}}$							
	$ V_{OUT}  \le 5V, T_J= 25^{\circ}C$		5	25		15	25	mV
Load Regulation <sup>4</sup>	V <sub>OUT</sub>   ≥ 5V, T <sub>J</sub> = 25°C		0.1	0.5		0.3	0.5	%
	V <sub>OUT</sub>   ≤ 5V		10	50		20	50	mV
	V <sub>OUT</sub>  ≥5V		0.2	1		0.3	1	%
Thermal Regulation <sup>5</sup>	T <sub>J</sub> = 25°C, 10ms pulse		0.002	0.02		0.002	0.02	%/W
	V <sub>OUT</sub> = -10V, f =120Hz							
Ripple Rejection	$C_{ADJ} = 0, T_J = 25^{\circ}C$	60	66			60		dB
	C <sub>ADJ</sub> = 10µF	70	80		66	77		dB
Adjust Pin Current	$T_A = 25^{\circ}C$		65	100		65	100	μA
Adjust Pin Current	$3V \le  V_{IN} - V_{OUT}  \le 40V$		1.0	5		2	5	μA
Change <sup>6</sup>	$10\text{mA} \le I_{\text{OUT}} \le I_{\text{MAX}}$		0.2	2		0.5	5	μA
Minimum Load	$ V_{IN} - V_{OUT}  \le 40V$		2.5	5.0		2.5	5.0	mA
Current	V <sub>IN</sub> - V <sub>OUT</sub>   ≤ 10V		1.2	3		1.2	3.0	mA
	V <sub>IN</sub> - V <sub>OUT</sub>   ≤ 15V							
Current Limit	K, IG Packages	1.5	2.2	3.2	1.5	2.2		А
	T, L, Packages	0.5	0.8	1.5	0.5	0.8		А

Symbol	Tast Osmilitians	SGR137A			SGR137			
Symbol	Test Conditions	Min.	Тур.	Max	Min.	Тур.	Max	Units
	$ V_{IN} - V_{OUT}  \le 40V, T_J = 25^{\circ}C$							
Current Limit	K, IG Packages	0.24	0.4	1.0	0.24	0.4		А
	T, L, Packages	0.15	0.25	0.5	0.15	0.25		А
Temperature Stability <sup>5</sup>			0.6	1.5		0.6		%
Long Term Stability <sup>5</sup>	T <sub>J</sub> = 125°C, 1000 Hours		0.3	1		0.3	1	%
RMS Output Noise (% of $V_{OUT}$ ) $T_J = 25^{\circ}C$ , $10Hz \le f \le 10kHz^5$			0.003			0.003		%

Notes:

4. Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output voltage due to heating effects are covered under the specification for thermal regulation.

5. These parameters, although guaranteed, are not tested in production

6.  $I_{MAX}$  for K, and IG packages is  $V_{IN} - V_{OUT} = 3V/1.5A$  and  $V_{IN} - V_{OUT} = 40V/240mA$ . For T and L packages  $I_{MAX}$  is  $V_{IN} - V_{OUT} = 3V/500mA$  and  $V_{IN} - V_{OUT} = 40V/150mA$ .



### **Characteristic Curves**



Figure 3 - Input/Output Differential vs. Output Current



Figure 5 - Current Vs. Input/Output Differential







Figure 4 - Reference Voltage Vs. Temperature



Figure 6 - Output Voltage Deviation Vs. Output Current\*



Figure 8 - Adjustment Current Vs. Temperature

*Notes:* \*The SGR137A has load regulation compensation which makes the typical unit read close to zero. This band represents the typical production spread.

## **Application Information**

#### **Output Voltage**

The output voltage is determined by two external resistors, R1 and R2



Figure 9 - Output Voltage

The exact formula for the output voltage is:

$$V_{OUT} = V_{REF} \left( \frac{R_2 + R_1}{R_1} \right) + I_{ADJ} (R_2)$$

Where:  $V_{REF}$  =Reference Voltage and  $I_{ADJ}$  = Adjustment Pin Current. In most applications, the second term is small enough to be ignored, typically about 0.5% of  $V_{OUT}$ . In more critical applications, the exact formula should be used, with  $I_{ADJ}$  equal to 65 µA. Solving for  $R_2$  yields:

$$R_2 = \frac{V_{OUT} - V_{REF}}{\frac{V_{REF}}{R_1} + I_{ADJ}}$$

Smaller values of  $R_1$  and  $R_2$  reduce the influence of  $I_{ADJ}$  on the output voltage, but the no-load current drain on the regulator is increased. Typical values for  $R_1$  are between 100  $\Omega$  and 300  $\Omega$ , giving 12.5mA and 4.2mA no-load current. There is an additional consideration in selecting  $R_1$  the minimum load current specification of the regulator. The operating current of the SGR137A flows from input to output. If this current is not absorbed by the load, the output of the regulator rises above the regulated value. The current drawn by  $R_1$  and  $R_2$  is normally high enough to absorb the current, but care must be taken in no–load situations where  $R_1$  and  $R_2$  have high values. The maximum value for the operating current, which must be absorbed, is 5mA for the SGR137A. If input and output voltage differential is less than 10V, the operating current that must be absorbed drops to 3mA.

Examples:

- 1. A precision 10V regulator to supply up to 1 Amp load current.
  - a. Select  $R_1 = 100\Omega$  to minimize effect of  $I_{ADJ}$
  - b. Calculate  $R_2 = \frac{V_{OUT} V_{REF}}{(V_{REF}/R_1) + I_{ADJ}} = \frac{10V 1.25V}{(1.25V/100 \text{ ohms}) + 65\mu A} = 704 \text{ ohms}$

A 15 V regulator to run off batteries and supply 50mA.  $V_{IN}$  MAX = 25V

c. To minimize battery drain, select R1 as high as possible

$$R_1 = \frac{1.25V}{3mA} = 417\Omega$$
, use 404 $\Omega$ , 1%



## **Typical Application Circuits**

The output stability, load regulation, line regulation, thermal regulation, temperature drift, long term drift, and noise can be improved by a factor of 6.6 over the standard regulator configuration. This assumes a zener whose drift and noise is considerably better than the regulator itself. The LM329B has 20PPM/°C maximum drift and about 10 times lower noise than the regulator.

In the application as shown figure 10, regulators #2 to #N tracks regulator #1 to within  $\pm 24$  mV initially, and to  $\pm 60$  mV over all load, line, and temperature conditions. If any regulator output is shorted to ground, all other outputs drop to -2V. Load regulation of regulators #2 to #N are improved by V<sub>OUT</sub>/1.25 V compared to a standard regulator, so regulator #1 should be the one which has the lowest load current.





Figure 11 · Multiple Tracking Regulators





Figure 12 - Current Regulator



Figure 13 - Dual Tracking Supply ±1.25 V To ±20 V



### Package Outline Dimensions

Controlling dimensions are in inches, metric equivalents are shown for general information.



Dim	MILLIMETERS		INC	HES
Dim	MIN	MAX	MIN	MAX
D	8.89	9.40	0.350	0.370
D1	8.13	8.51	0.320	0.335
Α	4.19	4.70	0.165	0.185
b	0.41	0.48	0.016	0.019
F	-	1.02	-	0.040
е	5.08	BSC	0.200 BSC	
k	0.71	0.86	0.028	0.034
k1	0.74	1.14	0.029	0.045
L	12.70	14.48	0.500	0.570
α	45° 1	ΓYΡ	45°	TYP
e1	2.54	TYP	0.10	0 TYP
b1	0.41	0.53	0.016	0.021
Q	90° 1	ГҮР	90°	TYP
L1	-	1.27	-	0.50

Figure 14 - T 3-Pin Metal Can TO-39 Package Dimensions



Dim	MILLIMETERS		INCHES		
Dim	MIN	MAX	MIN	MAX	
D/E	8.64	9.14	0.340	0.360	
E3	-	8.128	-	0.320	
е	1.270	BSC	0.050 BSC		
B1	0.635	TYP	0.025 TYP		
L	1.02	1.52	0.040	0.060	
А	1.626	2.286	0.064	0.090	
h	1.016 TYP		0.04	0 TYP	
A1	1.372	1.68	0.054	0.066	
A2	-	1.168	-	0.046	
L2	1.91	2.41	0.075	0.95	
B3	0.20	3R	0.008R		

Note:

1. All exposed metalized area shall be gold plated 60 micro-inch minimum thickness over nickel plated unless otherwise specified in purchase order.

Figure 15 · L 20-Pin Ceramic Leadless Chip Carrier (LCC) Package Dimensions



# Package Outline Dimensions



Dim	MILLIMETERS		INC	HES		
	MIN	MAX	MIN	MAX		
А	4.70	5.21	0.185	0.205		
A1	0.89	1.14	0.035	0.045		
A2	2.92	3.18	0.115	0.125		
b	0.71	.081	0.027	0.032		
D	16.38	16.76	0.645	0.660		
D1*	10.41	10.92	0.410	0.430		
е	2.54	BSC	0.100 BSC			
E*	10.41	10.67	0.410	0.420		
Н		0.50		0.020		
L	12.70		0.500			
0	13.39	13.64	0.527	0.537		
Р	3.56	3.81	0.140	0.150		
J		0.10		0.004		
V	5.13	5.38	0.202	0.212		
Z	1.40	1.40 TYP 0.055 TYP				
*Exclude	es Weld Fille	et Around Li	d.			

Figure 16 - G/IG 3-Pin Hermetic TO-257 Package Dimensions



Dim	MILLIMETERS		INC	HES
Dim	MIN	MAX	MIN	MAX
А	6.86	7.62	0.270	0.300
q	29.90	30.40	1.177	1.197
b	0.97	1.09	0.038	0.043
D	19.43	19.68	0.765	0.775
S	16.64	17.14	0.655	0.675
е	10.67	11.18	0.420	0.440
E1	5.21	5.72	0.205	0.225
F	1.52	2.03	0.060	0.080
R1	3.84	4.09	0.151	0.161
L	10.79	12.19	0.425	0.480
R	12.57	13.34	0.495	0.525

Figure 17 · K 3-Pin TO-3 Package Dimension



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